

GP1A58HRJ00F

Gap: 5mm, Slit: 0.5mm
*OPIC Output
Case package Transmissive
Photointerrupter



■ Description

GP1A58HRJ00F is a standard, OPIC output, transmissive photointerrupter with opposing emitter and detector in a case, providing non-contact sensing. For this family of devices, the emitter and detector are inserted in a case, resulting in a through-hole design.

This device has a wide gap and positioning pins.

■ Features

- 1. Transmissive with OPIC output
- 2. Highlights:
 - Vertical Slit for alternate motion detection
 - Output Low Level at intercepting optical path
 - Positioning Pin to prevent misalignment
- 3. Key Parameters:
 - · Gap Width: 5mm
 - · Slit Width (detector side): 0.5mm
 - Package: 13.7×10×5.2mm
- 4. RoHS directive compliant

■ Agency approvals/Compliance

1. Compliant with RoHS directive

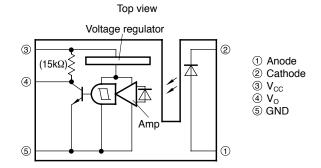
■ Applications

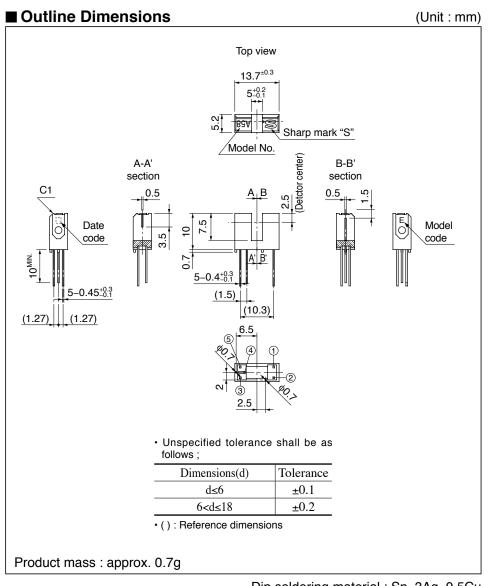
- General purpose detection of object presence or motion.
- 2. Example: Printer, FAX, Optical storage unit

^{* &}quot;OPIC"(Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and a signalprocessing



■ Internal Connection Diagram





Dip soldering material : Sn-3Ag-0.5Cu



Date code		
Month of production		
Month	Mark	
1	1	
2	2	
3	3	
4	4	
5	5	
6	6	
7	7	
8	8	
9	9	
10	X	
11	Y	
12	Z	

Model code	Year of production
Wiodei code	(Christian year)
Е	Even year
e	Odd year

Country of origin

Japan, Indonesia or Philippines (Indicated on the packing case)



Absolute Maximum Ratings $(T_a=25^{\circ}C)$				
	Parameter	Symbol	Rating	Unit
*1 Forward current		I_{F}	50	mA
Innut	*1, ² Peak forward current	I_{FM}	1	A
прис	Input Reverse voltage		6	V
	Power dissipation	P	75	mW
	Supply voltage	V_{CC}	-0.5 to +17	V
Output	Output current	I_{O}	50	mA
	Power dissipation	Po	250	mW
Operating temperature		Topr	-25 to +85	°C
Storage temperature		T_{stg}	-40 to +100	°C
*3Soldering temperature		T _{sol}	260	°C

■ Electro-optical Characteristics

 $(T_a=25^{\circ}C)$

		Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
	1		-		IVIIIV.		-	_
Input		Forward voltage	V_{F}	$I_F=8mA$	_	1.14	1.4	V
прис		Reverse current	I_R	$V_R=3V$	_	_	10	μΑ
		Operating supply voltage	V_{CC}	-	4.5	_	17	V
		Low level output voltage	V_{OL}	$V_{CC}=5V, I_{OL}=16mA, I_{F}=0$	_	0.15	0.4	V
Output		High level output voltage	V_{OH}	V_{CC} =5V, I_F =8mA	4.9	_	_	V
Low level supply current	I_{CCL}	$V_{CC}=5V$, $I_{F}=0$	_	1.7	3.8	mA		
		High level supply current	I_{CCH}	V_{CC} =5V, I_F =8mA	_	0.7	2.2	mA
	*4	"Low→High" threshold input current	I_{FLH}	$V_{CC}=5V$	_	1	8	mA
Transfer	*5]	Hysteresis	I_{FLH}/I_{FHL}	$V_{CC}=5V$	0.55	0.75	0.95	_
	*6	"Low-High" Propagation delay time	t _{PLH}	V_{CC} =5V, I_F =8mA, R_L =280 Ω	_	3	9	
	Responce time	"High→Low" Propagation delay time	t_{PHL}		_	5	15	μs
teristics		Rise time	t _r		_	0.1	0.5	
	Res	Fall time	$t_{\rm f}$		_	0.05	0.5	

^{*4} I_{FLH} represents forward current when output goes from "Low" to "High". *5 I_{FHL} represents forward current when output goes from "High" to "Low". *6 Test circuit for response time is shown in Fig.12.

^{*1} Refer to Fig. 1, 2, 3 *2 Pulse width \leq 100 μ s, Duty ratio=0.01

^{*3} For 5s or less



Fig.1 Forward Current vs.

Ambient Temperature

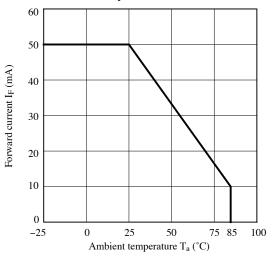


Fig.3 Low Level Output Current vs.
Ambient Temperature

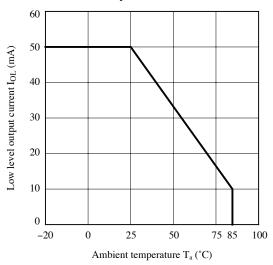


Fig.5 Relative Threshold Input Current vs. Supply Voltage

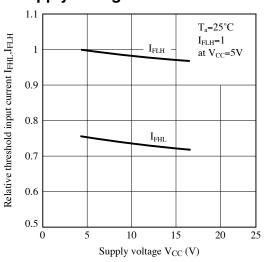


Fig.2 Output Power Dissipation vs. Ambient Temperature

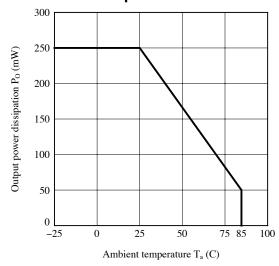


Fig.4 Forward Current vs. Forward Voltage

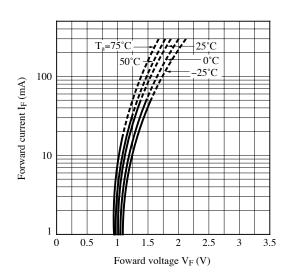


Fig.6 Relative Threshold Input Current vs. Ambient Temperature

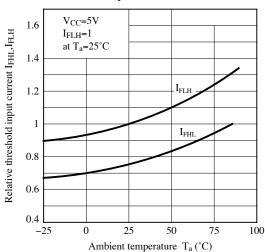




Fig.7 Low Level Output Voltage vs. Low Level Output Current

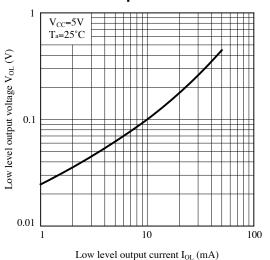


Fig.9 Supply Current vs.

Ambient Temperature

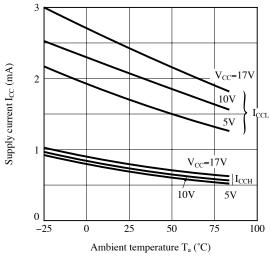


Fig.11 Rise Time,Fall Time vs. Load Resistance

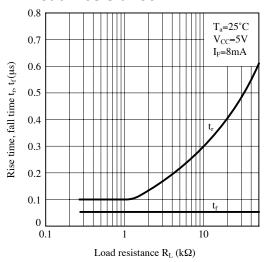


Fig.8 Low Level Output Voltage vs. Ambient Temperature

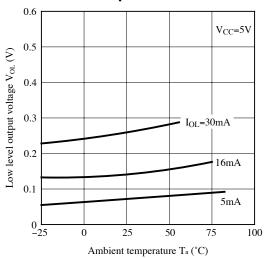


Fig.10 Propagation Delay Time vs. Forward Current

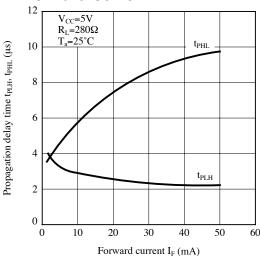
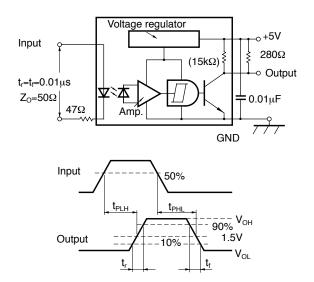


Fig.12 Test Circuit for Response Time



Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



■ Design Considerations

Recommended operating conditions

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Output current	Io	_	_	16	mA
Forward current	I_{F}	10	_	20	mA
Operating terperature	Topr	0	_	70	°C

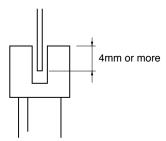
Notes about static electricity

Transisiter of detector side in bipolar configuration may be damaged by static electricity due to its minute design.

When handing these devices, general countermeasure against static electricity should be taken to avoid breakdown of devices or degradation of characteristics.

Design guide

- 1) Prevention of detection error
 - To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.
- 2) In order to stabilize power supply line, connect a by-pass capacitor of more than $0.01\mu F$ between V_{CC} and GND near the device.
- 3) Position of opaque board
 - Opaque board shall be installed at place 4mm or more from the top of elements. (Example)



This product is not designed against irradiation and incorporates non-coherent IRED.

Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.



Parts

This product is assembled using the below parts.

• Photodetector (qty. : 1) [Using a silicon photodiode as light detecting portion, and a bipolar IC as signal processing circuit]

Category	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (µs)
Photodiode	900	400 to 1 200	3

• Photo emitter (qty.: 1)

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	950	0.3

Material

Case	Lead frame plating
Black NORYL resin	Solder dip. (Sn-3Ag-0.5Cu)

Others

Laser generator is not used.



■ Manufacturing Guidelines

Soldering Method

Flow Soldering:

Soldering should be completed below 260°C and within 5 s.

Please take care not to let any external force exert on lead pins.

Please don't do soldering with preheating, and please don't do soldering by reflow.

Hand soldering

Hand soldering should be completed within 3 s when the point of solder iron is below 350°C.

Please solder within one time.

Please don't touch the terminals directly by soldering iron.

Soldered product shall treat at normal temperature.

Other notice

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the cooling and soldering conditions.

Flux

Some flux, which is used in soldering, may crack the package due to synergistic effect of alcohol in flux and the rise in temperature by heat in soldering. Therefore, in using flux, please make sure that it does not have any influence on appearance and reliability of the photointerrupter.



Cleaning instructions

Solvent cleaning:

Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.

Ultrasonic cleaning:

The effect to device by ultrasonic cleaning differs by cleaning bath size, ultrasonic power output, cleaning time, PCB size or device mounting condition etc.

Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).



■ Package specification

Case package

Package materials

Anti-static plastic bag: Polyethtylene

Moltopren: Urethane

Partition: Corrugated fiberboard
Packing case: Corrugated fiberboard

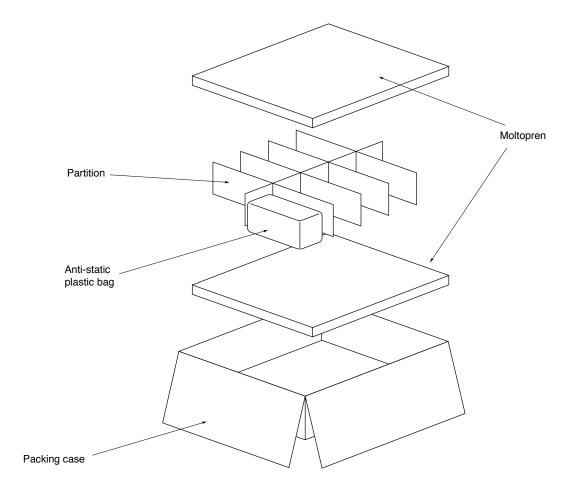
Package method

100 pcs of products shall be packaged in a plastic bag, Ends shall be fixed by stoppers. The bottom of the packing case is covered with moltopren, and the partition is set in the packing case. Each partition should have 1 plastic bag.

The 10 plastic bags containing a product are put in the packing case.

Moltopren should be located after all product are settled (1 packing contains 1 000 pcs).

Packing composition





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